

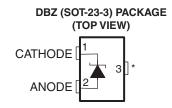
# PRECISION MICROPOWER SHUNT VOLTAGE REFERENCE

#### **FEATURES**

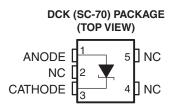
- Fixed Output Voltages of 2.5 V, 4.096 V, 5 V, and 10 V
- Tight Output Tolerances and Low Temperature Coefficient
  - Max 0.1%, 50 ppm/°C A Grade
  - Max 0.2%, 50 ppm/°C B Grade
  - Max 0.5%, 50 ppm/°C C Grade
- Low Output Noise: 41 μV<sub>RMS</sub> Typ
- Wide Operating Current Range:
   60 μA Typ to 15 mA
- Stable With All Capacitive Loads; No Output Capacitor Required
- Available in Extended Temperature Range: -40°C to 125°C

#### **APPLICATIONS**

- Data-Acquisition Systems
- Power Supplies and Power-Supply Monitors
- Instrumentation and Test Equipment
- Process Controls
- Precision Audio
- Automotive Electronics
- Energy Management
- Battery-Powered Equipment



\*Pin 3 is attached to Substrate and must be connected to ANODE or left open.



NC - No internal connection

#### **DESCRIPTION/ORDERING INFORMATION**

The TL4050 series of shunt voltage references are versatile easy-to-use references suitable for a wide array of applications. The two-terminal fixed-output device requires no external capacitors for operation and is stable with all capacitive loads. Additionally, the reference offers low dynamic impedance, low noise, and low temperature coefficient to ensure a stable output voltage over a wide range of operating currents and temperatures.

The TL4050 is offered in three initial tolerances, ranging from 0.1% (max) for the A grade to 0.5% (max) for the C grade. Thus, a great deal of flexibility is offered to designers in choosing the best cost-to-performance ratio for their applications. Packaged in the space-saving SOT-23-3 and SC-70 packages and requiring a minimum current of  $45 \mu A$  (typ), the TL4050 also is ideal for portable applications.

The TL4050xl is characterized for operation over an ambient temperature range of -40°C to 85°C. The TL4050xQ is characterized for operation over an ambient temperature range of -40°C to 125°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



# ORDERING INFORMATION(1)

T <sub>A</sub>	DEVICE GRADE	V <sub>KA</sub>	PACK	AGE <sup>(2)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING <sup>(3)</sup>
			007.00.0 DD7	Reel of 3000	TL4050A25IDBZR	TIVE
		2.5 V	SOT-23-3 – DBZ	Reel of 250	TL4050A25IDBZT	TKE_
		2.5 V	00 70 DOK	Reel of 3000	TL4050A25IDCKR	00
			SC-70 – DCK	Reel of 250	TL4050A25IDCKT	82_
			COT 02 2 DD7	Reel of 3000	TL4050A41IDBZR	TIZI
		4.000.1/	SOT-23-3 – DBZ	Reel of 250	TL4050A41IDBZT	TKL_
	A grade: 0.1% initial	4.096 V	CC 70 DCV	Reel of 3000	TL4050A41IDCKR	o.c
	accuracy and		SC-70 – DCK	Reel of 250	TL4050A41IDCKT	
	50 ppm/°C		007.00.0 DD7	Reel of 3000	TL4050A50IDBZR	TICO
	temperature coefficient	5 V	SOT-23-3 – DBZ	Reel of 250	TL4050A50IDBZT	TKS_
		5 V	SC-70 – DCK	Reel of 3000	TL4050A50IDCKR	OI.
			SC-70 - DCK	Reel of 250	TL4050A50IDCKT	8L_
			COT 00 0 DD7	Reel of 3000	TL4050A10IDBZR	TVO
		40.1/	SOT-23-3 – DBZ	Reel of 250	TL4050A10IDBZT	TK2_
		10 V	00 70 DOK	Reel of 3000	TL4050A10IDCKR	0.7
400C to 050C			SC-70 – DCK	Reel of 250	TL4050A10IDCKT	8Z_
–40°C to 85°C			COT 00 0 DD7	Reel of 3000	TL4050B25IDBZR	TIVE
		0.5.1/	SOT-23-3 – DBZ	Reel of 250	TL4050B25IDBZT	TKF_
		2.5 V	00.70 001/	Reel of 3000	TL4050B25IDCKR	00
			SC-70 – DCK	Reel of 250	TL4050B25IDCKT	83_
			007.00.0 DD7	Reel of 3000	TL4050B41IDBZR	TICNA
		4.000.1/	SOT-23-3 – DBZ	Reel of 250	TL4050B41IDBZT	TKM_
	B grade: 0.2% initial	4.096 V	00.70 DOV	Reel of 3000	TL4050B41IDCKR	05
	accuracy and		SC-70 – DCK	Reel of 250	TL4050B41IDCKT	8F_
	50 ppm/°C		007.00.0 DD7	Reel of 3000	TL4050B50IDBZR	TICT
	temperature coefficient	<b>5</b> ) /	SOT-23-3 – DBZ	Reel of 250	TL4050B50IDBZT	TKT_
	3333.2.10	5 V	00 70 DOV	Reel of 3000	TL4050B50IDCKR	014
			SC-70 – DCK	Reel of 250	TL4050B50IDCKT	
			207.00.0 555	Reel of 3000	TL4050B10IDBZR	TICO
			SOT-23-3 – DBZ	Reel of 250	TL4050B10IDBZT	— ТК3_
		10 V	22 72 721/	Reel of 3000	TL4050B10IDCKR	
			SC-70 – DCK	Reel of 250	TL4050B10IDCKT	92_

<sup>(1)</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

<sup>(2)</sup> Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

<sup>(3)</sup> The actual top-side marking has one additional character that designates the wafer fab/assembly site.



# **ORDERING INFORMATION (continued)**

T <sub>A</sub>	DEVICE GRADE	V <sub>KA</sub>	PACKA	GE <sup>(2)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING <sup>(3)</sup>
			007.00.0 DD7	Reel of 3000	TL4050C25IDBZR	TICO
		251	SOT-23-3 – DBZ	Reel of 250	TL4050C25IDBZT	TKG_
		2.5 V	CC 70 DCV	Reel of 3000	TL4050C25IDCKR	84_
			SC-70 – DCK	Reel of 250	TL4050C25IDCKT	04_
			COT 22 2 DD7	Reel of 3000	TL4050C41IDBZR	TIZNI
		4.096 V	SOT-23-3 – DBZ	Reel of 250	TL4050C41IDBZT	TKN_
	C grade: 0.5% initial	4.096 V	SC-70 – DCK	Reel of 3000	TL4050C41IDCKR	8G_
–40°C to 85°C	accuracy and		30-70 - DCK	Reel of 250	TL4050C41IDCKT	00_
-40 C to 65 C	50 ppm/°C		SOT-23-3 – DBZ	Reel of 3000	TL4050C50IDBZR	TIZLI
	temperature coefficient	5 V	301-23-3 – DBZ	Reel of 250	TL4050C50IDBZT	TKU_
		5 V	SC-70 – DCK	Reel of 3000	TL4050C50IDCKR	8N
			30-70 - DCK	Reel of 250	TL4050C50IDCKT	OIN_
			SOT-23-3 – DBZ	Reel of 3000	TL4050C10IDBZR	TK4
		10 V	301-23-3 – DBZ	Reel of 250	TL4050C10IDBZT	1K4_
		10 V	CC 70 DCV	Reel of 3000	TL4050C10IDCKR	02
			SC-70 – DCK	Reel of 250	TL4050C10IDCKT	93_
			SOT-23-3 – DBZ	Reel of 3000	TL4050A25QDBZR	TKH_
		2.5 V	301-23-3 – DBZ	Reel of 250	TL4050A25QDBZT	TKII_
		2.5 V	SC-70 – DCK	Reel of 3000	TL4050A25QDCKR	95
			3C-70 - DCK	Reel of 250	TL4050A25QDCKT	85_
			SOT-23-3 – DBZ	Reel of 3000	TL4050A41QDBZR	TKP_
		4.096 V	301-23-3 – DBZ	Reel of 250	TL4050A41QDBZT	TKF_
	A grade: 0.1% initial	4.096 V	SC-70 – DCK	Reel of 3000	TL4050A41QDCKR	8H
–40°C to 125°C	accuracy and		30-70 - DCK	Reel of 250	TL4050A41QDCKT	оп_
-40 C to 125 C	50 ppm/°C		SOT-23-3 – DBZ	Reel of 3000	TL4050A50QDBZR	TKV_
	temperature coefficient	5 V	301-23-3 – DBZ	Reel of 250	TL4050A50QDBZT	TKV_
		o v	SC-70 – DCK	Reel of 3000	TL4050A50QDCKR	
			30-70 - DCK	Reel of 250	TL4050A50QDCKT	or_
			COT 22 2 DD7	Reel of 3000	TL4050A10QDBZR	TVE
		10.1/	SOT-23-3 – DBZ	Reel of 250	TL4050A10QDBZT	—TK5
		10 V	SC 70 DCV	Reel of 3000	TL4050A10QDCKR	04
			SC-70 – DCK	Reel of 250	TL4050A10QDCKT	94_

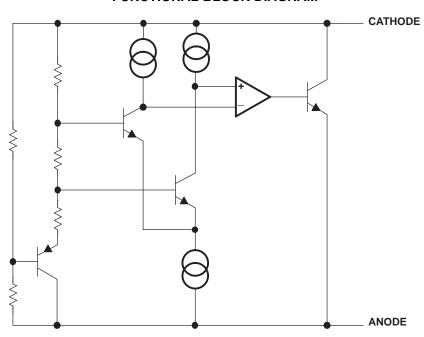


# **ORDERING INFORMATION (continued)**

T <sub>A</sub>	DEVICE GRADE	V <sub>KA</sub>	PACKA	AGE <sup>(2)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING <sup>(3)</sup>
			007.00.0 DD7	Reel of 3000	TL4050B25QDBZR	TICL
		0.5.1/	SOT-23-3 – DBZ	Reel of 250	TL4050B25QDBZT	TKJ_
		2.5 V	CC 70 DCV	Reel of 3000	TL4050B25QDCKR	00
			SC-70 – DCK	Reel of 250	TL4050B25QDCKT	86_
			COT 22 2 DD7	Reel of 3000	TL4050B41QDBZR	TVO
		4.096 V	SOT-23-3 – DBZ	Reel of 250	TL4050B41QDBZT	TKQ_
	B grade: 0.2% initial	4.096 V	SC-70 – DCK	Reel of 3000	TL4050B41QDCKR	8J
	accuracy and		3C-70 - DCK	Reel of 250	TL4050B41QDCKT	03_
	50 ppm/°C		SOT-23-3 – DBZ	Reel of 3000	TL4050B50QDBZR	TIZAZ
	temperature coefficient	5 V	SU1-23-3 - DBZ	Reel of 250	TL4050B50QDBZT	TKW_
		5 V	SC-70 – DCK	Reel of 3000	TL4050B50QDCKR	8R
			3C-70 - DCK	Reel of 250	TL4050B50QDCKT	or_
–40°C to 125°C			SOT-23-3 – DBZ	Reel of 3000	TL4050B10QDBZR	TK6
		10 V	301-23-3 - DBZ	Reel of 250	TL4050B10QDBZT	IKO_
		10 V	SC-70 – DCK	Reel of 3000	TL4050B10QDCKR	05
			3C-70 - DCK	Reel of 250	TL4050B10QDCKT	95_
			SOT-23-3 – DBZ	Reel of 3000	TL4050C25QDBZR	TKK_
		2.5 V	301-23-3 - DBZ	Reel of 250	TL4050C25QDBZT	TKK_
		2.5 V	SC-70 – DCK	Reel of 3000	TL4050C25QDCKR	07
			3C-70 - DCK	Reel of 250	TL4050C25QDCKT	87_
			SOT-23-3 – DBZ	Reel of 3000	TL4050C41QDBZR	TKR_
		4.096 V	301-23-3 - DBZ	Reel of 250	TL4050C41QDBZT	TKK_
	C grade: 0.5% initial	4.090 V	SC-70 – DCK	Reel of 3000	TL4050C41QDCKR	8K
	accuracy and		3C-70 - DCK	Reel of 250	TL4050C41QDCKT	or_
	50 ppm/°C temperature		SOT-23-3 – DBZ	Reel of 3000	TL4050C50QDBZR	TKY
	coefficient	5 V	301-23-3 = DBZ	Reel of 250	TL4050C50QDBZT	IKI_
		J V	SC-70 – DCK	Reel of 3000	TL4050C50QDCKR	8S
			50-70 - DON	Reel of 250	TL4050C50QDCKT	00_
			SOT-23-3 – DBZ	Reel of 3000	TL4050C10QDBZR	TK7
		10 V	301-23-3 - DBZ	Reel of 250	TL4050C10QDBZT	11/1_
		10 V	SC-70 – DCK	Reel of 3000	TL4050C10QDCKR	96_
			30-70 - DON	Reel of 250	TL4050C10QDCKT	30_



#### **FUNCTIONAL BLOCK DIAGRAM**



## ABSOLUTE MAXIMUM RATINGS(1)

over free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
IZ	Continuous cathode current		-10	20	mA
0	Package thermal impedance <sup>(2)(3)</sup>	DBV package		206	°C/W
$\theta_{JA}$	Package thermal impedance (-)	DCK package		252	C/VV
TJ	Operating virtual junction temperature			150	°C
T <sub>stg</sub>	Storage temperature range		-65	150	°C

Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## RECOMMENDED OPERATING CONDITIONS

			MIN	MAX	UNIT
$I_Z$	Cathode current		(1)	15	mA
т	Eron air temperature	I temperature	-40	85	°C
¹A	Free-air temperature	Q temperature	-40	125	C

(1) See parametric tables

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Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability. The package thermal impedance is calculated in accordance with JESD 51-7.



# TL4050x25I ELECTRICAL CHARACTERISTICS

at industrial temperature range, full range  $T_A = -40$  °C to 85°C (unless otherwise noted)

		TEGT CONDITIONS	_	TL4	1050A25I		TL	4050B25I		TL	4050C25I		UNIT
P	ARAMETER	TEST CONDITIONS	T <sub>A</sub>	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNII
Vz	Reverse breakdown voltage	Ι <sub>Z</sub> = 100 μΑ	25°C		2.5			2.5			2.5		V
	Reverse		25°C	-2.5		2.5	<b>-</b> 5		5	-13		13	
$\Delta V_Z$	breakdown voltage tolerance	I <sub>Z</sub> = 100 μA	Full range	-11		11	-14		14	-21		21	mV
	Minimum		25°C		41	60		41	60		41	60	
$I_{Z,min}$	cathode current		Full range			65			65			65	μΑ
	Average	I <sub>Z</sub> = 10 mA	25°C		±20			±20			±20		
	temperature coefficient of	$I_Z = 1 \text{ mA}$	25°C		±15			±15			±15		
$\alpha_{\text{VZ}}$	reverse		25°C		±15			±15			±15		ppm/°C
	breakdown voltage	I <sub>Z</sub> = 100 μA	Full range			±50			±50			±50	
			25°C		0.3	0.8		0.3	0.8		0.3	0.8	
$\Delta V_Z$	Reverse breakdown voltage change	$I_{Z,min} < I_Z < 1 \text{ mA}$	Full range			1.2			1.2			1.2	mV
$\Delta I_Z$	with cathode		25°C		2.3	6		2.3	6		2.3	6	IIIV
	current change	1 mA < I <sub>Z</sub> < 15 mA	Full range			8			8			8	
Z <sub>Z</sub>	Reverse dynamic impedance	$I_Z = 1 \text{ mA},$ f = 120  Hz, $I_{AC} = 0.1 I_Z$	25°C		0.3			0.3			0.3		Ω
e <sub>N</sub>	Wideband noise	$I_Z = 100 \mu A$ , 10 Hz \le f \le 10 kHz	25°C		41			41			41		$\mu V_{RMS}$
	Long-term stability of reverse breakdown voltage	t = 1000 h, T <sub>A</sub> = 25°C ± 0.1°C, I <sub>Z</sub> = 100 μA			120			120			120		ppm
V <sub>HYST</sub>	Thermal hysteresis (1)	$\Delta T_A = -40$ °C to 125°C			0.7			0.7			0.7		mV

<sup>(1)</sup> Thermal hysteresis is defined as  $V_{Z,25^{\circ}C}$  (after cycling to  $-40^{\circ}C$ ) –  $V_{Z,25^{\circ}C}$  (after cycling to  $125^{\circ}C$ ).



# TL4050x25Q ELECTRICAL CHARACTERISTICS

at extended temperature range, full range  $T_A = -40$ °C to 125°C (unless otherwise noted)

	AD AMETED	TEST COMPITIONS	-	TL4	050A25Q	ì	TL4	4050B250	)	TL4	1050C25C	ì	UNIT
-	PARAMETER	TEST CONDITIONS	T <sub>A</sub>	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNII
Vz	Reverse breakdown voltage	Ι <sub>Z</sub> = 100 μΑ	25°C		2.5			2.5			2.5		V
	Reverse		25°C	-2.5		2.5	-5		5	-13		13	
$\Delta V_Z$	breakdown voltage tolerance	I <sub>Z</sub> = 100 μA	Full range	-15		15	-18		18	-25		25	mV
	Minimum		25°C		41	60		41	60		41	60	
$I_{Z,min}$	cathode current		Full range			65			65			65	μΑ
	Average	I <sub>Z</sub> = 10 mA	25°C		±20			±20			±20		
	temperature coefficient of	$I_Z = 1 \text{ mA}$	25°C		±15			±15			±15		
$\alpha_{VZ}$	reverse		25°C		±15			±15			±15		ppm/°C
	breakdown voltage	I <sub>Z</sub> = 100 μA	Full range			±50			±50			±50	
			25°C		0.3	0.8		0.3	0.8		0.3	0.8	
$\Delta V_Z$	Reverse breakdown voltage change	$I_{Z,min} < I_Z < 1 \text{ mA}$	Full range			1.2			1.2			1.2	mV
$\Delta I_Z$	with cathode		25°C		2.3	6		2.3	6		2.3	6	IIIV
	current change	1 mA < I <sub>Z</sub> < 15 mA	Full range			8			8			8	
Z <sub>Z</sub>	Reverse dynamic impedance	$I_Z = 1 \text{ mA},$ f = 120  Hz, $I_{AC} = 0.1 I_Z$	25°C		0.3			0.3			0.3		Ω
e <sub>N</sub>	Wideband noise	$I_Z = 100 \mu A$ , 10 Hz \le f \le 10 kHz	25°C		41			41			41		$\mu V_{RMS}$
	Long-term stability of reverse breakdown voltage	t = 1000 h, T <sub>A</sub> = 25°C ± 0.1°C, I <sub>Z</sub> = 100 μA			120			120			120		ppm
V <sub>HYST</sub>	Thermal hysteresis (1)	$\Delta T_A = -40$ °C to 125°C			0.7			0.7			0.7		mV

<sup>(1)</sup> Thermal hysteresis is defined as  $V_{Z,25^{\circ}C}$  (after cycling to  $-40^{\circ}C$ ) –  $V_{Z,25^{\circ}C}$  (after cycling to  $125^{\circ}C$ ).

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# TL4050x41I ELECTRICAL CHARACTERISTICS

at industrial temperature range, full range  $T_A = -40$  °C to 85°C (unless otherwise noted)

_		TEGT CONDITIONS	_	TL	4050A41I		TL	4050B41I		TL	4050C41I		
P	ARAMETER	TEST CONDITIONS	T <sub>A</sub>	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
Vz	Reverse breakdown voltage	Ι <sub>Z</sub> = 100 μΑ	25°C		4.096			4.096			4.096		V
	Reverse		25°C	-4.1		4.1	-8.2		8.2	-21		21	
$\Delta V_Z$	breakdown voltage tolerance	I <sub>Z</sub> = 100 μA	Full range	-18		18	-22		22	-34		34	mV
	Minimum		25°C		52	68		52	68		52	68	
$I_{Z,min}$	cathode current		Full range			73			73			73	μΑ
	Average	I <sub>Z</sub> = 10 mA	25°C		±30			±30			±30		
	temperature coefficient of	$I_Z = 1 \text{ mA}$	25°C		±20			±20			±20		
$\alpha_{\text{VZ}}$	reverse		25°C		±20			±20			±20		ppm/°C
	breakdown voltage	I <sub>Z</sub> = 100 μA	Full range			±50			±50			±50	
			25°C		0.2	0.9		0.2	0.9		0.2	0.9	
$\Delta V_Z$	Reverse breakdown voltage change	$I_{Z,min} < I_Z < 1 \text{ mA}$	Full range			1.2			1.2			1.2	mV
$\Delta I_Z$	with cathode		25°C		2	7		2	7		2	7	IIIV
	current change	1 mA < I <sub>Z</sub> < 15 mA	Full range			10			10			10	
Z <sub>Z</sub>	Reverse dynamic impedance	$I_Z = 1 \text{ mA},$ f = 120  Hz, $I_{AC} = 0.1 I_Z$	25°C		0.5			0.5			0.5		Ω
e <sub>N</sub>	Wideband noise	$I_Z = 100 \mu A$ , 10 Hz $\leq f \leq 10 \text{ kHz}$	25°C		93			93			93		$\mu V_{\text{RMS}}$
	Long-term stability of reverse breakdown voltage	t = 1000 h, T <sub>A</sub> = 25°C ± 0.1°C, I <sub>Z</sub> = 100 μA			120			120			120		ppm
V <sub>HYST</sub>	Thermal hysteresis (1)	$\Delta T_A = -40$ °C to 125°C			1.148			1.148			1.148		mV

<sup>(1)</sup> Thermal hysteresis is defined as  $V_{Z,25^{\circ}C}$  (after cycling to  $-40^{\circ}C$ ) –  $V_{Z,25^{\circ}C}$  (after cycling to  $125^{\circ}C$ ).



# TL4050x41Q ELECTRICAL CHARACTERISTICS

at extended temperature range, full range  $T_A = -40$ °C to 125°C (unless otherwise noted)

				TI 4	1050A41C	)	TI A	4050B410	)	TI.	4050C41C	)	
P	PARAMETER	TEST CONDITIONS	T <sub>A</sub>	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
Vz	Reverse breakdown voltage	I <sub>Z</sub> = 100 μA	25°C		4.096			4.096			4.096		٧
	Reverse		25°C	-4.1		4.1	-8.2		8.2	-21		21	
$\Delta V_Z$	breakdown voltage tolerance	I <sub>Z</sub> = 100 μA	Full range	-25		25	-29		29	-41		41	mV
	Minimum		25°C		52	68		52	68		52	68	
$I_{Z,min}$	cathode current		Full range			78			78			78	μΑ
	Average	I <sub>Z</sub> = 10 mA	25°C		±30			±30			±30		
	temperature coefficient of	$I_Z = 1 \text{ mA}$	25°C		±20			±20			±20		
$\alpha_{\text{VZ}}$	reverse		25°C		±20			±20			±20		ppm/°C
	breakdown voltage	I <sub>Z</sub> = 100 μA	Full range			±50			±50			±50	
			25°C		0.2	0.9		0.2	0.9		0.2	0.9	
$\Delta V_Z$	Reverse breakdown voltage change	$I_{Z,min} < I_Z < 1 \text{ mA}$	Full range			1.2			1.2			1.2	mV
$\Delta I_Z$	with cathode		25°C		2	7		2	7		2	7	IIIV
	current change	1 mA < I <sub>Z</sub> < 15 mA	Full range			10			10			10	
Z <sub>Z</sub>	Reverse dynamic impedance	$I_Z = 1 \text{ mA},$ f = 120  Hz, $I_{AC} = 0.1 I_Z$	25°C		0.5			0.5			0.5		Ω
e <sub>N</sub>	Wideband noise	$I_Z = 100 \mu A$ , 10 Hz \le f \le 10 kHz	25°C		93			93			93		$\mu V_{RMS}$
	Long-term stability of reverse breakdown voltage	t = 1000 h, T <sub>A</sub> = 25°C ± 0.1°C, I <sub>Z</sub> = 100 μA			120			120			120		ppm
V <sub>HYST</sub>	Thermal hysteresis <sup>(1)</sup>	$\Delta T_A = -40$ °C to 125°C			1.148			1.148			1.148		mV

<sup>(1)</sup> Thermal hysteresis is defined as  $V_{Z,25^{\circ}C}$  (after cycling to  $-40^{\circ}C$ ) –  $V_{Z,25^{\circ}C}$  (after cycling to  $125^{\circ}C$ ).

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# TL4050x50I ELECTRICAL CHARACTERISTICS

at industrial temperature range, full range  $T_A = -40$  °C to 85°C (unless otherwise noted)

		TEGT CONDITIONS	_	TL4	050A50I		TL	4050B50I		TL	4050C50I		UNIT
P	ARAMETER	TEST CONDITIONS	TA	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNII
Vz	Reverse breakdown voltage	Ι <sub>Z</sub> = 100 μΑ	25°C		5			5			5		٧
	Reverse		25°C	<b>-</b> 5		5	-10		10	-25		25	
$\Delta V_Z$	breakdown voltage tolerance	I <sub>Z</sub> = 100 μA	Full range	-22		22	-27		27	-42		42	mV
	Minimum		25°C		56	74		56	74		56	74	
$I_{Z,min}$	cathode current		Full range			80			80			80	μΑ
	Average	I <sub>Z</sub> = 10 mA	25°C		±30			±30			±30		
	temperature coefficient of	$I_Z = 1 \text{ mA}$	25°C		±20			±20			±20		
$\alpha_{\text{VZ}}$	reverse		25°C		±20			±20			±20		ppm/°C
	breakdown voltage	I <sub>Z</sub> = 100 μA	Full range			±50			±50			±50	
			25°C		0.2	1		0.2	1		0.2	1	
$\Delta V_Z$	Reverse breakdown voltage change	$I_{Z,min} < I_Z < 1 \text{ mA}$	Full range			1.4			1.4			1.4	mV
$\Delta I_Z$	with cathode		25°C		2	8		2	8		2	8	1110
	current change	1 mA < I <sub>Z</sub> < 15 mA	Full range			12			12			12	
Z <sub>Z</sub>	Reverse dynamic impedance	I <sub>Z</sub> = 1 mA, f = 120 Hz, I <sub>AC</sub> = 0.1 I <sub>Z</sub>	25°C		0.5			0.5			0.5		Ω
e <sub>N</sub>	Wideband noise	$I_Z = 100 \mu A$ , 10 Hz $\leq f \leq 10 \text{ kHz}$	25°C		93			93			93		$\mu V_{\text{RMS}}$
	Long-term stability of reverse breakdown voltage	t = 1000 h, T <sub>A</sub> = 25°C ± 0.1°C, I <sub>Z</sub> = 100 μA			120			120			120		ppm
V <sub>HYST</sub>	Thermal hysteresis (1)	$\Delta T_A = -40^{\circ} \text{C to } 125^{\circ} \text{C}$			1.4			1.4			1.4		mV

<sup>(1)</sup> Thermal hysteresis is defined as  $V_{Z,25^{\circ}C}$  (after cycling to  $-40^{\circ}C$ ) –  $V_{Z,25^{\circ}C}$  (after cycling to  $125^{\circ}C$ ).

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## TL4050x50Q ELECTRICAL CHARACTERISTICS

at extended temperature range, full range  $T_A = -40$ °C to 125°C (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	-	TL4	050A50Q	ì	TL4	1050B50C	ì	TL4	050C50C	ì	UNIT
-	ARAMETER	TEST CONDITIONS	T <sub>A</sub>	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNII
Vz	Reverse breakdown voltage	Ι <sub>Z</sub> = 100 μΑ	25°C		5			5			5		V
	Reverse		25°C	<b>–</b> 5		5	-10		10	-25		25	
$\Delta V_Z$	breakdown voltage tolerance	I <sub>Z</sub> = 100 μA	Full range	-30		30	-35		35	-50		50	mV
	Minimum		25°C		56	74		56	74		56	74	
$I_{Z,min}$	cathode current		Full range			90			90			90	μА
	Average	I <sub>Z</sub> = 10 mA	25°C		±30			±30			±30		
	temperature coefficient of	I <sub>Z</sub> = 1 mA	25°C		±20			±20			±20		
$\alpha_{\text{VZ}}$	reverse		25°C		±20			±20			±20		ppm/°C
	breakdown voltage	I <sub>Z</sub> = 100 μA	Full range			±50			±50			±50	
			25°C		0.2	1		0.2	1		0.2	1	
$\Delta V_Z$	Reverse breakdown voltage change	$I_{Z,min} < I_Z < 1 \text{ mA}$	Full range			1.4			1.4			1.4	mV
$\Delta I_Z$	with cathode		25°C		2	8		2	8		2	8	IIIV
	current change	1 mA < I <sub>Z</sub> < 15 mA	Full range			12			12			12	
Z <sub>Z</sub>	Reverse dynamic impedance	$I_Z = 1 \text{ mA},$ f = 120  Hz, $I_{AC} = 0.1 I_Z$	25°C		0.5			0.5			0.5		Ω
e <sub>N</sub>	Wideband noise	$I_Z = 100 \mu A$ , 10 Hz \le f \le 10 kHz	25°C		93			93			93		$\mu V_{RMS}$
	Long-term stability of reverse breakdown voltage	t = 1000 h, T <sub>A</sub> = 25°C ± 0.1°C, I <sub>Z</sub> = 100 μA			120			120			120		ppm
V <sub>HYST</sub>	Thermal hysteresis (1)	$\Delta T_A = -40$ °C to 125°C			1.4			1.4			1.4		mV

<sup>(1)</sup> Thermal hysteresis is defined as  $V_{Z,25^{\circ}C}$  (after cycling to  $-40^{\circ}C$ ) –  $V_{Z,25^{\circ}C}$  (after cycling to  $125^{\circ}C$ ).

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# TL4050x10I ELECTRICAL CHARACTERISTICS

at industrial temperature range, full range  $T_A = -40$  °C to 85°C (unless otherwise noted)

_		TEST SOUDITIONS	_	TL	4050A10I		TL	4050B10	l	TL	4050C10I		
•	PARAMETER	TEST CONDITIONS	T <sub>A</sub>	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
Vz	Reverse breakdown voltage	Ι <sub>Z</sub> = 100 μΑ	25°C		10			10			10		V
	Reverse		25°C	-10		10	-20		20	-50		50	
$\Delta V_Z$	breakdown voltage tolerance	I <sub>Z</sub> = 100 μA	Full range	-43		43	-53		53	-83		83	mV
	Minimum		25°C		80	100		80	100		80	100	
I <sub>Z,min</sub>	cathode current		Full range			103			103			103	μΑ
	Average	I <sub>Z</sub> = 10 mA	25°C		±40			±40			±40		
	temperature coefficient of	I <sub>Z</sub> = 1 mA	25°C		±20			±20			±20		
$\alpha_{VZ}$	reverse		25°C		±20			±20			±20		ppm/°C
	breakdown voltage	I <sub>Z</sub> = 100 μA	Full range			±50			±50			±50	
			25°C		0.8	1.5		0.8	1.5		0.8	1.5	
$\Delta V_Z$	Reverse breakdown voltage change	$I_{Z,min} < I_Z < 1 \text{ mA}$	Full range			3.5			3.5			3.5	mV
$\Delta I_Z$	with cathode		25°C		8	12		8	12		8	12	IIIV
	current change	1 mA < I <sub>Z</sub> < 15 mA	Full range			23			23			23	
Z <sub>Z</sub>	Reverse dynamic impedance	$I_Z = 1 \text{ mA},$ f = 120  Hz, $I_{AC} = 0.1 I_Z$	25°C		0.7			0.7			0.7		Ω
e <sub>N</sub>	Wideband noise	$I_Z = 100 \mu A$ , 10 Hz \le f \le 10 kHz	25°C		150			150			150		$\mu V_{RMS}$
	Long-term stability of reverse breakdown voltage	t = 1000 h, T <sub>A</sub> = 25°C ± 0.1°C, I <sub>Z</sub> = 100 μA			120			120			120		ppm
V <sub>HYST</sub>	Thermal hysteresis (1)	$\Delta T_A = -40$ °C to 125°C			2.8			2.8			2.8		mV

<sup>(1)</sup> Thermal hysteresis is defined as  $V_{Z,25^{\circ}C}$  (after cycling to  $-40^{\circ}C$ ) –  $V_{Z,25^{\circ}C}$  (after cycling to  $125^{\circ}C$ ).



## TL4050x10Q ELECTRICAL CHARACTERISTICS

at extended temperature range, full range  $T_A = -40$ °C to 125°C (unless otherwise noted)

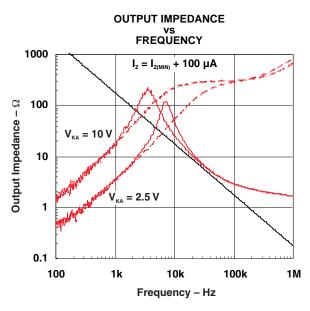
	PARAMETER	TEST CONDITIONS	_	TL4	1050A10C	ì	TL4	4050B100	2	TL4	1050C10C	ì	UNIT
•	ARAMETER	TEST CONDITIONS	T <sub>A</sub>	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNII
Vz	Reverse breakdown voltage	Ι <sub>Z</sub> = 100 μΑ	25°C		10			10			10		V
	Reverse		25°C	-10		10	-20		20	<b>-</b> 50		50	
$\Delta V_Z$	breakdown voltage tolerance	I <sub>Z</sub> = 100 μA	Full range	-60		60	-70		70	-100		100	mV
	Minimum		25°C		80	100		80	100		80	100	
$I_{Z,min}$	cathode current		Full range			110			110			110	μΑ
	Average	I <sub>Z</sub> = 10 mA	25°C		±40			±40			±40		
	temperature coefficient of	$I_Z = 1 \text{ mA}$	25°C		±20			±20			±20		
$\alpha_{\text{VZ}}$	reverse		25°C		±20			±20			±20		ppm/°C
	breakdown voltage	I <sub>Z</sub> = 100 μA	Full range			±50			±50			±50	
			25°C		0.8	1.5		0.8	1.5		0.8	1.5	
$\Delta V_Z$	Reverse breakdown voltage change	$I_{Z,min} < I_Z < 1 \text{ mA}$	Full range			3.5			3.5			3.5	mV
$\Delta I_Z$	with cathode		25°C		8	12		8	12		8	12	1110
	current change	1 mA < I <sub>Z</sub> < 15 mA	Full range			23			23			23	
Z <sub>Z</sub>	Reverse dynamic impedance	$I_Z = 1 \text{ mA},$ f = 120  Hz, $I_{AC} = 0.1 I_Z$	25°C		0.7			0.7			0.7		Ω
$e_N$	Wideband noise	$I_Z = 100 \mu A$ , 10 Hz \le f \le 10 kHz	25°C		150			150			150		$\mu V_{RMS}$
	Long-term stability of reverse breakdown voltage	t = 1000 h, T <sub>A</sub> = 25°C ± 0.1°C, I <sub>Z</sub> = 100 μA			120			120			120		ppm
V <sub>HYST</sub>	Thermal hysteresis (1)	$\Delta T_A = -40$ °C to 125°C			2.8			2.8			2.8		mV

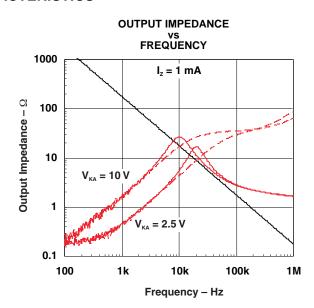
<sup>(1)</sup> Thermal hysteresis is defined as  $V_{Z,25^{\circ}C}$  (after cycling to  $-40^{\circ}C$ ) –  $V_{Z,25^{\circ}C}$  (after cycling to  $125^{\circ}C$ ).

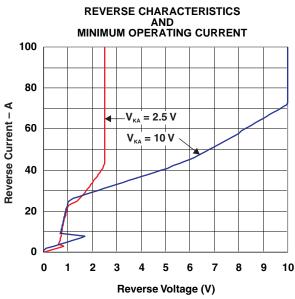
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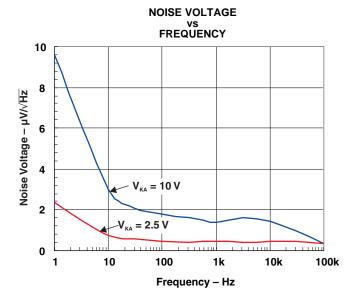


## **TYPICAL CHARACTERISTICS**



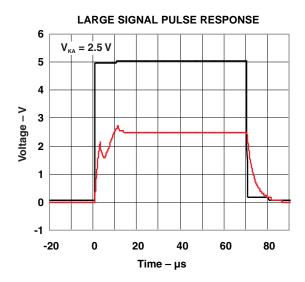


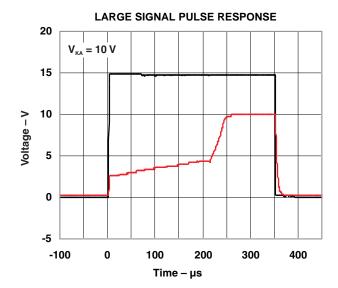






# **TYPICAL CHARACTERISTICS (continued)**







#### **APPLICATION INFORMATION**

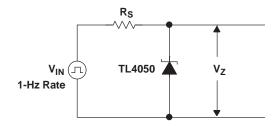


Figure 1. Start-Up Test Circuit

## **Output Capacitor**

The TL4050 does not require an output capacitor across cathode and anode for stability. However, if an output bypass capacitor is desired, the TL4050 is designed to be stable with all capacitive loads.

#### **SOT-23 Pin Connections**

There is a parasitic Schottky diode connected between pins 2 and 3 of the SOT-23 packaged device. Thus, pin 3 of the SOT-23 package must be left floating or connected to pin 2.

#### **Use With ADCs or DACs**

The TL4050x-41 is designed to be a cost-effective voltage reference as required in 12-bit data-acquisition systems. For 12-bit systems operating from 5-V supplies, such as the ADS7842 (see Figure 2), the TL4050x-41 (4.096 V) permits operation with an LSB of 1 mV.

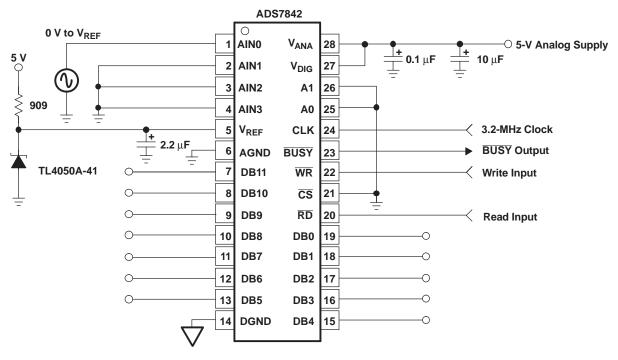


Figure 2. Data-Acquisition Circuit With TL4050x-41



#### **Cathode and Load Currents**

In a typical shunt-regulator configuration (see Figure 3), an external resistor,  $R_S$ , is connected between the supply and the cathode of the TL4050.  $R_S$  must be set properly, as it sets the total current available to supply the load ( $I_L$ ) and bias the TL4050 ( $I_Z$ ). In all cases,  $I_Z$  must stay within a specified range for proper operation of the reference. Taking into consideration one extreme in the variation of the load and supply voltage (maximum  $I_L$  and minimum  $V_S$ ),  $R_S$  must be small enough to supply the minimum  $I_Z$  required for operation of the regulator, as given by data-sheet parameters. At the other extreme, maximum  $V_S$  and minimum  $I_L$ ,  $R_S$  must be large enough to limit  $I_Z$  to less than its maximum-rated value of 15 mA.

 $R_S$  is calculated according to Equation 1:

$$R_{S} = \frac{(V_{S} - V_{Z})}{(I_{L} + I_{Z})} \tag{1}$$

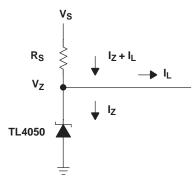


Figure 3. Shunt Regulator

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## **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TL4050A10IDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TK2U	Samples
TL4050A10IDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TK2U	Sample
TL4050A10IDCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	8ZU	Sample
TL4050A10IDCKT	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	8ZU	Sample
TL4050A10QDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	TK5U	Samples
TL4050A10QDCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	94U	Samples
TL4050A25IDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TKEU	Samples
TL4050A25IDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TKEU	Sample
TL4050A25IDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TKEU	Samples
TL4050A25IDCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	82U	Samples
TL4050A25IDCKT	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	82U	Samples
TL4050A25QDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	TKHU	Samples
TL4050A25QDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	TKHU	Samples
TL4050A25QDCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	85U	Sample
TL4050A41IDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(TKL3 ~ TKLU)	Sample
TL4050A41IDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(TKL3 ~ TKLU)	Samples
TL4050A41QDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(TKP3 ~ TKPU)	Samples





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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TL4050A41QDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(TKP3 ~ TKPU)	Samples
TL4050A41QDCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	8HU	Samples
TL4050A50IDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(TKS3 ~ TKSU)	Samples
TL4050A50IDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(TKS3 ~ TKSU)	Samples
TL4050A50IDCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	8LU	Samples
TL4050A50IDCKT	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	8LU	Samples
TL4050A50QDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(TKV3 ~ TKVU)	Samples
TL4050A50QDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(TKV3 ~ TKVU)	Samples
TL4050A50QDCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	8PU	Samples
TL4050B10IDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TK3U	Samples
TL4050B10IDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TK3U	Samples
TL4050B10QDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	TK6U	Samples
TL4050B10QDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	TK6U	Samples
TL4050B10QDCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	95U	Samples
TL4050B25IDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TKFU	Samples
TL4050B25IDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TKFU	Samples
TL4050B25IDCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	83U	Samples
TL4050B25QDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	TKJU	Samples



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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TL4050B25QDCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	86U	Samples
TL4050B41IDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TKMU	Samples
TL4050B41IDBZRG4	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TKMU	Samples
TL4050B41IDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TKMU	Samples
TL4050B41IDCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	8FU	Samples
TL4050B41IDCKT	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	8FU	Samples
TL4050B41QDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(TKQ3 ~ TKQU)	Samples
TL4050B41QDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(TKQ3 ~ TKQU)	Samples
TL4050B41QDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(TKQ3 ~ TKQU)	Samples
TL4050B50IDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(TKT3 ~ TKTU)	Samples
TL4050B50IDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(TKT3 ~ TKTU)	Samples
TL4050B50IDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(TKT3 ~ TKTU)	Samples
TL4050B50IDCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	8MU	Samples
TL4050B50QDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(TKW3 ~ TKWU)	Samples
TL4050B50QDCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	8RU	Sample
TL4050C10IDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(TK43 ~ TK4U)	Sample
TL4050C10IDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(TK43 ~ TK4U)	Sample
TL4050C10QDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(TK73 ~ TK7U)	Samples



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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TL4050C25IDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TKGU	Samples
TL4050C25IDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TKGU	Samples
TL4050C25IDBZTG4	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TKGU	Samples
TL4050C25IDCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	84U	Samples
TL4050C25IDCKT	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	84U	Samples
TL4050C25QDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	TKKU	Samples
TL4050C25QDCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	87U	Samples
TL4050C41IDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TKNU	Samples
TL4050C41IDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TKNU	Samples
TL4050C41IDCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	8GU	Samples
TL4050C41QDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	TKRU	Samples
TL4050C41QDCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	8KU	Samples
TL4050C41QDCKT	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	8KU	Samples
TL4050C50IDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(TKU3 ~ TKUU)	Samples
TL4050C50IDBZT	ACTIVE	SOT-23	DBZ	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(TKU3 ~ TKUU)	Samples
TL4050C50IDCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	8NU	Samples
TL4050C50IDCKT	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	8NU	Samples
TL4050C50QDBZR	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(TKY3 ~ TKYU)	Samples



# PACKAGE OPTION ADDENDUM

5-Aug-2016

Orderable Device	Status	Package Type	_	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
TL4050C50QDCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	8SU	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF TL4050C50:



# **PACKAGE OPTION ADDENDUM**

5-Aug-2016

• Automotive: TL4050C50-Q1

NOTE: Qualified Version Definitions:

• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

**PACKAGE MATERIALS INFORMATION** 

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# TAPE AND REEL INFORMATION





	Α0	Dimension designed to accommodate the component width
	B0	Dimension designed to accommodate the component length
	K0	Dimension designed to accommodate the component thickness
	W	Overall width of the carrier tape
г	D1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL4050A10IDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050A10IDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050A10IDCKR	SC70	DCK	5	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050A10IDCKT	SC70	DCK	5	250	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050A10QDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050A10QDCKR	SC70	DCK	5	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050A25IDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050A25IDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050A25IDCKR	SC70	DCK	5	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050A25IDCKT	SC70	DCK	5	250	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050A25QDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050A25QDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050A25QDCKR	SC70	DCK	5	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050A41IDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050A41QDCKR	SC70	DCK	5	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050A50IDCKR	SC70	DCK	5	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050A50IDCKT	SC70	DCK	5	250	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050A50QDCKR	SC70	DCK	5	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3



# **PACKAGE MATERIALS INFORMATION**

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Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL4050B10IDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050B10IDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050B10QDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050B10QDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050B10QDCKR	SC70	DCK	5	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050B25IDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050B25IDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050B25IDCKR	SC70	DCK	5	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050B25QDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050B25QDCKR	SC70	DCK	5	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050B41IDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050B41IDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050B41IDCKR	SC70	DCK	5	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050B41IDCKT	SC70	DCK	5	250	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050B41QDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050B50IDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050B50IDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050B50IDCKR	SC70	DCK	5	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050B50QDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050B50QDCKR	SC70	DCK	5	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050C10IDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050C25IDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050C25IDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050C25IDCKR	SC70	DCK	5	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050C25IDCKT	SC70	DCK	5	250	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050C25QDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050C25QDCKR	SC70	DCK	5	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050C41IDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050C41IDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050C41IDCKR	SC70	DCK	5	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050C41QDBZR	SOT-23	DBZ	3	3000	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050C41QDCKR	SC70	DCK	5	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050C41QDCKT	SC70	DCK	5	250	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050C50IDBZT	SOT-23	DBZ	3	250	179.0	8.4	3.15	2.95	1.22	4.0	8.0	Q3
TL4050C50IDCKR	SC70	DCK	5	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050C50IDCKT	SC70	DCK	5	250	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TL4050C50QDCKR	SC70	DCK	5	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3



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\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL4050A10IDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
TL4050A10IDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
TL4050A10IDCKR	SC70	DCK	5	3000	203.0	203.0	35.0
TL4050A10IDCKT	SC70	DCK	5	250	203.0	203.0	35.0
TL4050A10QDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
TL4050A10QDCKR	SC70	DCK	5	3000	203.0	203.0	35.0
TL4050A25IDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
TL4050A25IDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
TL4050A25IDCKR	SC70	DCK	5	3000	203.0	203.0	35.0
TL4050A25IDCKT	SC70	DCK	5	250	203.0	203.0	35.0
TL4050A25QDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
TL4050A25QDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
TL4050A25QDCKR	SC70	DCK	5	3000	203.0	203.0	35.0
TL4050A41IDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
TL4050A41QDCKR	SC70	DCK	5	3000	203.0	203.0	35.0
TL4050A50IDCKR	SC70	DCK	5	3000	203.0	203.0	35.0
TL4050A50IDCKT	SC70	DCK	5	250	203.0	203.0	35.0
TL4050A50QDCKR	SC70	DCK	5	3000	203.0	203.0	35.0
TL4050B10IDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
TL4050B10IDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0



# **PACKAGE MATERIALS INFORMATION**

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL4050B10QDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
TL4050B10QDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
TL4050B10QDCKR	SC70	DCK	5	3000	203.0	203.0	35.0
TL4050B25IDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
TL4050B25IDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
TL4050B25IDCKR	SC70	DCK	5	3000	203.0	203.0	35.0
TL4050B25QDBZR	SOT-23	DBZ	3	3000	195.0	200.0	45.0
TL4050B25QDCKR	SC70	DCK	5	3000	203.0	203.0	35.0
TL4050B41IDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
TL4050B41IDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
TL4050B41IDCKR	SC70	DCK	5	3000	203.0	203.0	35.0
TL4050B41IDCKT	SC70	DCK	5	250	203.0	203.0	35.0
TL4050B41QDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
TL4050B50IDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
TL4050B50IDBZT	SOT-23	DBZ	3	250	195.0	200.0	45.0
TL4050B50IDCKR	SC70	DCK	5	3000	203.0	203.0	35.0
TL4050B50QDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
TL4050B50QDCKR	SC70	DCK	5	3000	203.0	203.0	35.0
TL4050C10IDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
TL4050C25IDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
TL4050C25IDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
TL4050C25IDCKR	SC70	DCK	5	3000	203.0	203.0	35.0
TL4050C25IDCKT	SC70	DCK	5	250	203.0	203.0	35.0
TL4050C25QDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
TL4050C25QDCKR	SC70	DCK	5	3000	203.0	203.0	35.0
TL4050C41IDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
TL4050C41IDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
TL4050C41IDCKR	SC70	DCK	5	3000	203.0	203.0	35.0
TL4050C41QDBZR	SOT-23	DBZ	3	3000	203.0	203.0	35.0
TL4050C41QDCKR	SC70	DCK	5	3000	203.0	203.0	35.0
TL4050C41QDCKT	SC70	DCK	5	250	203.0	203.0	35.0
TL4050C50IDBZT	SOT-23	DBZ	3	250	203.0	203.0	35.0
TL4050C50IDCKR	SC70	DCK	5	3000	203.0	203.0	35.0
TL4050C50IDCKT	SC70	DCK	5	250	203.0	203.0	35.0
TL4050C50QDCKR	SC70	DCK	5	3000	203.0	203.0	35.0

# DCK (R-PDSO-G5)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-203 variation AA.



# DCK (R-PDSO-G5)

# PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



# DBZ (R-PDSO-G3)

# PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Lead dimensions are inclusive of plating.
- D. Body dimensions are exclusive of mold flash and protrusion. Mold flash and protrusion not to exceed 0.25 per side.
- Falls within JEDEC TO-236 variation AB, except minimum foot length.



# DBZ (R-PDSO-G3)

# PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



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